

SUBMINIATURE SOLID STATE LAMP

HYPER RED AM27SURCK08

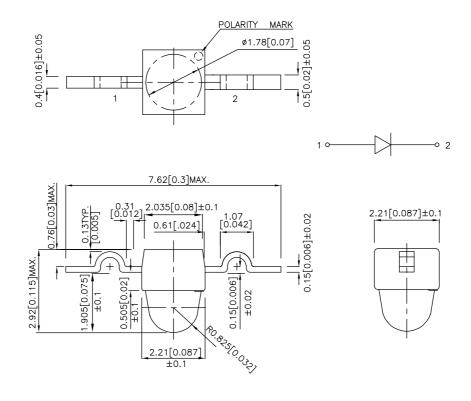
Features

- •SUBMINIATURE PACKAGE.
- •WIDE VIEWING ANGLE.
- •YOKE LEAD.
- •LONG LIFE-SOLID STATE RELIABILITY.
- •LOW PACKAGE PROFILE.
- •PACKAGE: 1000PCS/REEL.
- •RoHS COMPLIANT.

Description

The Hyper Red source color devices are made with DH InGaAIP on GaAs substrate Light Emitting Diode.

Package Dimensions



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25 (0.01")$ unless otherwise noted.
- 3. Lead spacing is measured where the lead emerge from the package.4. Specifications are subject to change without notice.

SPEC NO: DSAD1313 **REV NO: V.2** DATE: MAR/10/2005 **PAGE: 1 OF 4** APPROVED: J. Lu CHECKED: Allen Liu **DRAWN: S.H.CHEN** ERP:1202000397

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Selection Guide

Part No.	Dice	Lens Type	lv (m @ 20	,	Viewing Angle
			Min. Typ.		201/2
AM27SURCK08	HYPER RED (InGaAIP)	WATER CLEAR	180	650	20°

Note

Electrical / Optical Characteristics at Ta=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red	650		nm	IF=20mA
λD	Dominant Wavelength	Hyper Red	635		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red	28		nm	IF=20mA
С	Capacitance	Hyper Red	35		pF	VF=0V;f=1MHz
VF	Forward Voltage	Hyper Red	1.95	2.5	V	IF=20mA
lR	Reverse Current	Hyper Red		10	uA	VR= 5V

Absolute Maximum Ratings at T_A=25°C

Parameter	Hyper Red	Units
Power dissipation	170	mW
DC Forward Current	30	mA
Peak Forward Current [1]	185	mA
Reverse Voltage	5	V
Operating / Storage Temperature	e Temperature -40°C To +85°C	

Note

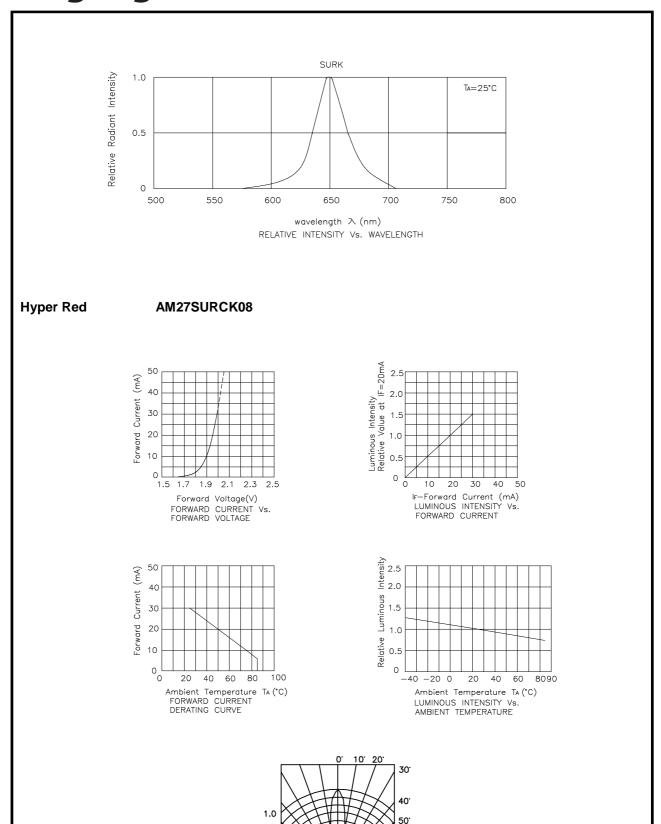
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^{1.} θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

^{1. 1/10} Duty Cycle, 0.1ms Pulse Width.

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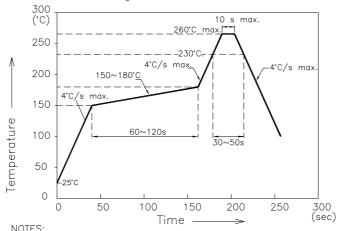
SPATIAL DISTRIBUTION

60° 70° 80° 90°

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AM27SURCK08

Reflow Soldering Profile For Lead-free SMT Process.

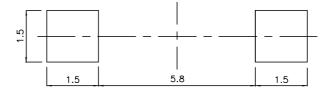


- NOTES:

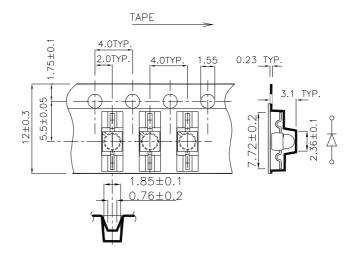
 1.We recommend the reflow temperature 245°C(±5°C).The maximum soldering temperature should be limited to 260°C.

 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
 - 3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm)



Tape Specifications (Units: mm)



Remarks:

If there is sorting requirement (eg. forward voltage, luminous intensity or wavelength), the condition as follows:

- 1. Wavelength: +/-1nm (Test condition is based on the sorting standard).
- 2.Luminous intensity: +/-15% (Test condition is based on the sorting standard).
- 3. Forward voltage: +/-0.1V (Test condition is based on the sorting standard).

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